ABSTRACT

SEMICONDUCTOR DEVICE

A semiconductor device comprises a lead frame having a die pad portion or a circuit board, one or more semiconductor elements mounted on the die pad portion of the lead frame or on the circuit board, a copper wire that electrically connects electrical joints provided on the lead frame or the circuit board to an electrode pad provided on the semiconductor element, and an encapsulating member which encapsulates the semiconductor element and the copper wire, wherein the electrode pad and/or the encapsulating member having predetermined properties are combined with the copper wire having predetermined properties.

Fig. None